



Please note that Cypress is an Infineon Technologies Company.

The document following this cover page is marked as “Cypress” document as this is the company that originally developed the product. Please note that Infineon will continue to offer the product to new and existing customers as part of the Infineon product portfolio.

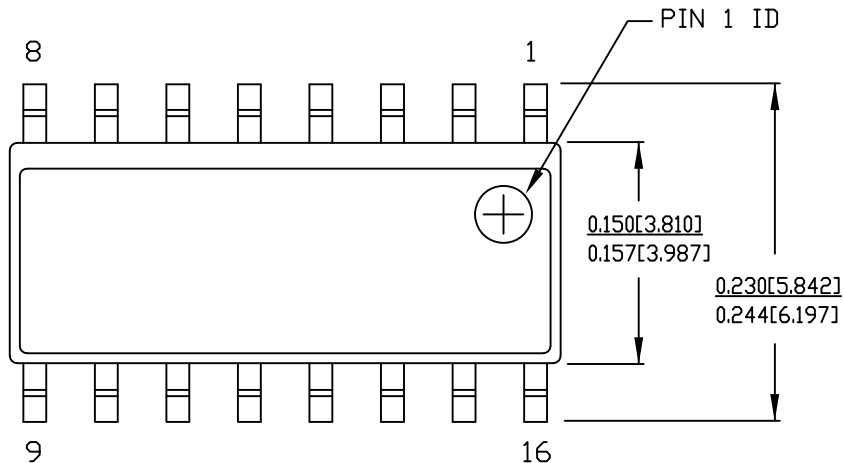
Continuity of document content

The fact that Infineon offers the following product as part of the Infineon product portfolio does not lead to any changes to this document. Future revisions will occur when appropriate, and any changes will be set out on the document history page.

Continuity of ordering part numbers

Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.

16 Lead (150 Mil) SOIC

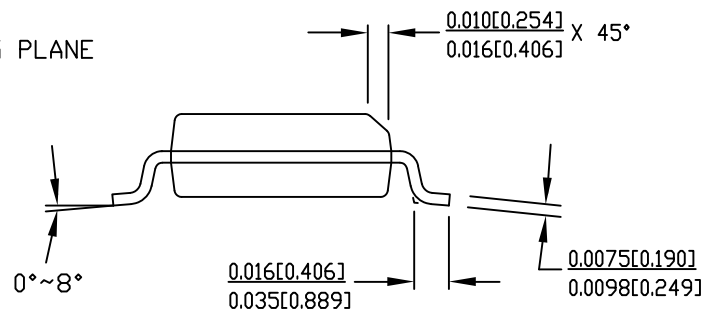
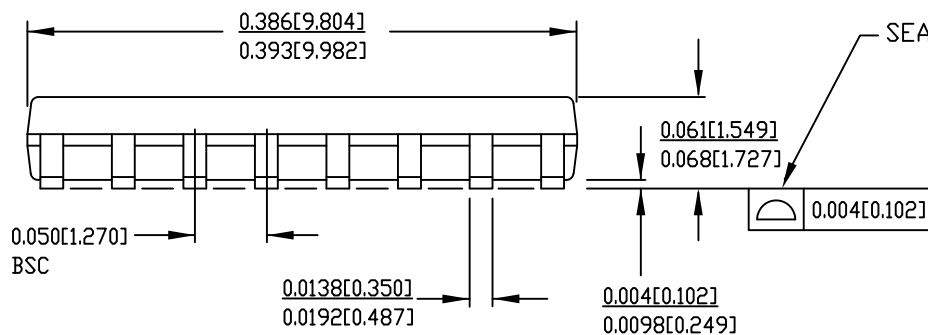


REVISIONS						
PAGE	ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
1	-	**	1129	NEW RELEASE	02/23/95	N/A
1	-	*A	49416	CHG. TITLE	04/03/97	N/A
1	-	*B	128915	ADD MM DIM./ ADD JEDEC #/ ADD SZ PART # / ADD PACKAGE WEIGHT	08/05/03	N/A
1	-	*C	2780429	CHANGED TO STANDARD DWG./TITLE FROM 16LD (150 MIL) SOIC PKG PACKAGE OUTLINE, 16L SOIC 150 MIL S16.15/SZ16.15.	10/07/09	BZG
1	-	*D	3357783	Update spec for sunset review no change	08/30/11	QAD
1	-	*E	3735784	Changed pkg. weight 0.15gm to "refer to PMDD spec 001-04308"	09/05/12	QAD
1	-	*F	6547476	Changed Note #3 to refer to IPC 1752 Material Declaration	04/16/19	RODP


NOTE:

1. DIMENSIONS IN INCHES[MM] MIN./MAX.
2. REFERENCE JEDEC MS-012
3. PACKAGE WEIGHT : refer to IPC 1752 Material Declaration.

PART #	
S16.15	STANDARD PKG.
SZ16.15	LEAD FREE PKG.



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UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN MILLIMETERS STANDARD TOLERANCES ARE: DECIMALS .XX ± 0.05 .XXX ± .XXXX + ANGLES ± 1°	DESIGNED BY HTN	DATE 08/05/03	 CYPRESS Company Confidential				
	DRAWN BY KOTA	DATE 04/16/19					
	CHECKED BY RODP	DATE 04/16/19	TITLE PACKAGE OUTLINE, 16L SOIC 150 MIL S16.15/SZ16.15				
	APPROVED BY RODP	DATE 04/16/19	<table border="1"> <tr> <td>SIZE A</td> <td>PART NO. S16.15/SZ16.15</td> <td>DWG NO 51-85068</td> <td>REV *F</td> </tr> </table>	SIZE A	PART NO. S16.15/SZ16.15	DWG NO 51-85068	REV *F
SIZE A	PART NO. S16.15/SZ16.15	DWG NO 51-85068	REV *F				
MATERIAL N/A	APPROVED BY ECM	DATE 04/16/19	<table border="1"> <tr> <td>SCALED TO FIT</td> <td>N/A</td> <td>SHEET 1</td> <td>OF 1</td> </tr> </table>	SCALED TO FIT	N/A	SHEET 1	OF 1
SCALED TO FIT	N/A	SHEET 1	OF 1				
FINISH N/A	APPROVED BY	DATE					